



S/N 10/612,764

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| | | | |
|-------------|---|-----------------|----------------|
| Applicant: | Vassoudevane Lebonheur et al. | Examiner: | Victor Mandala |
| Serial No.: | 10/612,764 | Group Art Unit: | 2826 |
| Filed: | June 30, 2003 | Docket: | 884.862US1 |
| Title: | MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME | | |
| Assignee: | Intel Corporation | Customer No: | 21186 |

RESPONSE TO RESTRICTION REQUIREMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Restriction Requirement mailed April 7, 2005, Applicants hereby elect, with traverse, Subspecies I (Fig. 2). Claims 1-5 and 7-30 are readable on Species I.

Traversal of this restriction is based upon what Applicant considers incorrect criteria regarding FIGs. 2-4. There are two criteria for imposing a restriction requirement. Criteria for restriction between patentably distinct inventions include "(A) The inventions must be independent; and (B) There must be a serious burden on the examiner if restriction is required" (M.P.E.P. § 803).

"Applicant cites to the specification for support of this consideration:

By review of FIGs. 2, 3, and 4, the molding compound cap encroachments 226, 326, and 426, respectively, are depicted as about 25%, 80%, and 0%. Any percentage of the die height, however, is contemplated as an embodiment, so long as the percentage is a fraction of 100% including zero percent.

Applicant respectfully asserts that there is no serious burden to examine claims that describe the structures in FIGs. 2, 3, and 4, because as a minimum, they represent quantitative differences about mold cap height on the dice, that are not likely found in different subclasses within the classification system of the United States Patent and Trademark Office. Withdrawal of the restriction requirement is respectfully requested.

RESPONSE TO RESTRICTION REQUIREMENT

Serial Number: 10/612,764

Filing Date: June 30, 2003

Title: MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME

Assignee: Intel Corporation

Page 2

Dkt: 884.862US1

The Examiner is invited to telephone Applicant's attorney, John Greaves at (801) 278-9171, or Applicant's below-named representative to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

VASSOUDEVANE LEBONHEUR ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, Minnesota 55402
(612) 349-9592

Date May 9, 2005

By Ann M. McCrackin

Ann M McCrackin

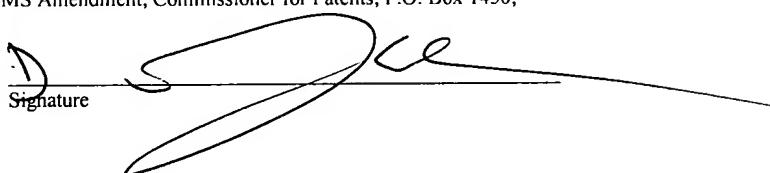
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this May 9 day of May 2005.

Name

Dennis J. Kemph

Signature



INFORMATION DISCLOSURE STATEMENT

Serial No :10/612,764

Filing Date: June 30, 2003

Title: MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME

Assignee: Intel Corporation

Page 2

Dkt: 884.862US1

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicants believe that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicants have not included copies of any U.S. Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicants respectfully request that notice of such requirement be directed to Applicants' below-signed representative. Applicants acknowledge the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

VASSOUDEVANE LEBONHEUR ET AL.

By their Representatives,

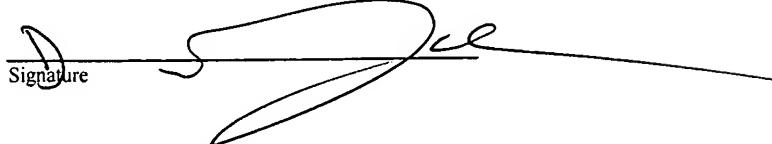
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9592

Date May 9, 2005

By Ann M. McCrackin
Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 9 day of May 2005.

Dennis J. Kemp
Name


Signature